

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)

2. (Currently Amended) ~~The wiring board as defined in claim 1, wherein A~~
wiring board comprising:

_____ a substrate;

_____ a bank which is disposed above the substrate to provide a plurality of regions;

and

_____ a conductive layer and first and second interconnecting lines formed between
the substrate and the bank,

_____ the bank having a top surface and a pair of side surfaces provided on both
sides of the top surface,

_____ the side surfaces sloping symmetrically with respect to the substrate,

the first interconnecting line ~~is-being~~ formed in a position closer to the substrate than the second interconnecting line, and the vertical centerline of the first interconnecting line ~~is-not coincide~~ coinciding with the vertical centerline of the second interconnecting line;

the conductive layer ~~is-being~~ formed in a position closer to the substrate than the second interconnecting line, and the vertical centerline of the conductive layer ~~is-not coincide~~ coinciding with the vertical centerline of the second interconnecting line; and

the conductive layer and the first interconnecting line respectively ~~have~~ having portions which are not located under the second interconnecting line, and the portions ~~extend~~ extending in opposite width directions.

3. (Currently Amended) The wiring board as defined in claim 2,
~~wherein~~ the lengths of the portions of the conductive layer and the first interconnecting line not located under the second interconnecting line are being equal.
4. (Currently Amended) The wiring board as defined in claim 2,
~~wherein~~ the second interconnecting line is being disposed right under the bank and within a range corresponding to the distance between the side surfaces of the bank.
5. (Currently Amended) The wiring board as defined in claim 4, ~~wherein:~~
the bank ~~includes~~ including a first bank portion formed of an inorganic material, and a second bank portion formed of an organic material on the first bank portion;
and
the second interconnecting line is being disposed right under the first and second bank portions within a range corresponding to the distance between the side surfaces of the bank.
6. (Currently Amended) The wiring board as defined in claim 4, ~~wherein:~~
a depression is being formed in the substrate; and
the conductive layer and the first interconnecting line ~~are being~~ disposed within the depression so as not to project above the surface of the substrate.
7. (Currently Amended) The wiring board as defined in ~~claim 1~~ claim 2,
~~wherein~~ the conductive layer is being one of electrodes of a capacitor.
8. (Currently Amended) The wiring board as defined in ~~claim 1~~ claim 2,
~~wherein~~ the first and second interconnecting lines are being respectively a signal line and a power supply line.
9. (Currently Amended) ~~The wiring board as defined in claim 1, wherein A~~
wiring board comprising:
a substrate;

a bank which is disposed above the substrate to provide a plurality of regions;
and

a conductive layer and first and second interconnecting lines formed between
the substrate and the bank,

the bank having a top surface and a pair of side surfaces provided on both
sides of the top surface,

the side surfaces sloping symmetrically with respect to the substrate,

the first interconnecting line ~~constitutes~~ constituting a part of a first drive
circuit, and

the conductive layer and the second interconnecting line constituting a part of
a second drive circuit.

10. (Currently Amended) The wiring board as defined in claim 6, ~~wherein:~~
the first interconnecting line ~~constitutes~~ constituting a part of a first drive
circuit; and

the conductive layer and the second interconnecting line ~~constitute~~ constituting
a part of a second drive circuit.

11. (Currently Amended) An electro-optical device comprising:
the wiring board as defined in ~~claim 1~~ claim 2; and
a functional layer disposed in each of the regions provided by the bank.

12. (Original) An electro-optical device comprising:
the wiring board as defined in claim 6; and
a functional layer disposed in each of the regions provided by the bank.

13. (Original) An electro-optical device comprising:
the wiring board as defined in claim 10; and
a functional layer disposed in each of the regions provided by the bank.

14. (Original) An electronic instrument comprising the electro-optical device as defined in claim 11.

15. (Original) An electronic instrument comprising the electro-optical device as defined in claim 12.

16. (Original) An electronic instrument comprising the electro-optical device as defined in claim 13.

17. (Currently Amended) A method of manufacturing an electro-optical device comprising:

forming the wiring board as defined in ~~claim 1~~ claim 2; and

forming a functional layer by disposing a liquid material including a functional layer material in each of the regions provided by the bank.

18. (Original) A method of manufacturing an electro-optical device comprising:
forming the wiring board as defined in claim 6; and
forming a functional layer by disposing a liquid material including a functional layer material in each of the regions provided by the bank.

19. (Original) A method of manufacturing an electro-optical device comprising:
forming the wiring board as defined in claim 10; and
forming a functional layer by disposing a liquid material including a functional layer material in each of the regions provided by the bank.